

Filename: PMP5270_REVC_bom.xls						
Date: 02/11/2014						
<b>PMP5270_REVC BOM</b>						
COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C21	47pF	Capacitor, Ceramic, 50V, C0G, 10%	603	Std	Std
1	C23	0.015uF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
4	C1, C2, C3, C4	0.01uF	Capacitor, Ceramic, 100V, X7R, 10%	603	Std	Std
1	C22	0.068uF	Capacitor, Ceramic, 25V, X7R, 10%	603	Std	Std
1	C18	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
0	C17	DNP	Capacitor, Ceramic, 100V, C0G, 10%	603	Std	Std
1	C8	220pF	Capacitor, Ceramic, 100V, C0G, 10%	805	Std	Std
1	C5	1000pF	Capacitor, Ceramic, 100V, X7R, 10%	805	Std	Std
2	C6, C12	0.1uF	Capacitor, Ceramic, 100V, X7R, 10%	805	Std	Std
2	C15, C24	1uF	Capacitor, Ceramic, 25V, X7R, 10%	805	Std	Std
0	C20	DNP	Capacitor, Ceramic, 200V, C0G, 10%	805	Std	Std
2	C10, C11	2.2uF	Capacitor, Ceramic, 100V, X7R, 10%	1210	Std	Std
4	C13, C16, C25, C26	22uF	Capacitor, Ceramic, 25V, X5R, 10%	1210	Std	TDK
1	C7	1000pF	Capacitor, Ceramic, 2kV, X7R 10%	1808	C4520X7R3D102K	TDK
1	C19	2200pF	Capacitor, Ceramic, 2KV, X7R, 20%	1812	C4532X7R3D222K	TDK
1	C9	22uF	Capacitor, Aluminum, 100V, 20%	8x10.2mm	EEVFK2A220P	Panasonic
1	D1		Diode, TVS, 58-V, 1W	SMA	SMAJ58A	Diodes Inc.
0	D10	ALT	Diode, Schottky, 8.0-A,35-V,	TO-252AA	MBRD835L	On Semi
1	D11		Diode, Schottky, 3A, 60V	SMC	MBRS360T3	On Semi
2	D2, D3		Bridge Rectifier, 100V, 0.8A	MINI DIP4	HD01	Diodes, Inc
2	D6, D9		Rectifier, Ultrafast Power, 200V 1A	SMA	MURA120T3	On Semi
1	D7		Diode, Switching, 150V, 200mA, 250mW,	SOD-123	BAV20W	Diodes, Inc
1	D8		Diode, Dual Ultra Fast, Series, 200-mA, 70-V	SOT23	BAV99	Fairchild
2	FB1, FB2		Bead, Ferrite, SMT, 600 Ohms, 2A	805	MPZ2012S601A	TDK
2	J1, J2		Connector, Jack, Modular, 8 POS	0.705 x 0.820	5520252-4	AMP
2	J3, J4		Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
1	L1	3.3uH	Inductor, SMT, 1.4A, 80milliohm	4x4mm	LPS4018-332ML	Coilcraft
1	Q1		MOSFET, N-ch, 150V, 3.7A, 85milliohms	SO8	Si4848DY	Vishay
1	R12	0	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R13	4.7	Resistor, Chip, 1/16W, 5%	603	Std	Std
4	R1, R2, R3, R4	75	Resistor, Chip, 1/16W, 5%	603	Std	Std
1	R11	90.9	Resistor, Chip, 1/16W,1%	603	Std	Std
1	R19	100	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R24	750	Resistor, Chip, 1/16W,1%	603	Std	Std
1	R22	2K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R15	2.87K	Resistor, Chip, 1/16W,1%	603	Std	Std
1	R25	4.02K	Resistor, Chip, 1/16W,1%	603	Std	Std
2	R16, R17	10K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R27	17.8K	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R21, R23	20K	Resistor, Chip, 1/16W, 1%	603	Std	Std

1	R7	24.9K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R9	60.4K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R10	100K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R26	392K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R8	20	Resistor, Chip, 1/10W, 5%	805	Std	Std
1	R6	24K	Resistor, Chip, 1/10W, 5%	805	Std	Std
1	R20	0.2	Resistor, Chip, 1/4W, 1%	1206	Std	Std
1	R5	47	Resistor, Chip, 1/4 watt, 5%	1206	Std	Std
1	R100	0	Resistor, Chip, 1/2W, 5%	2010	Std	Std
0	R18	DNP	Resistor, Chip, 1/2W, 5%	2010	Std	Std
1	T1		Xfmr, Center-tapped, Voice Over IP	0.500 x 0.370	H2019	Pulse
1	T2		Transformer, Flyback, 15V	0.677 x 0.865 inch	HA4137-AL	Coilcraft
0		ALT T3	Transformer, Flyback ±10%	0.551 x 0.695 inch	PA1528NL	Pulse
2	TP1, TP2		Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	TP4		Test Point, White, Thru Hole	0.125 x 0.125 inch	5012	Keystone
1	U2		IC, Photocoupler, 3750VRMS, 80-160% CTR	MF4	TCMT1107	Vishay
1	U3		IC, Precision Adjustable Shunt Regulator	SOT23-5	TL431AIDBVR	TI
1	U1		IC, IEEE 802.3af Integrated Primary Side Controller	TSSOP14	TPS23753APW	TI

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